L Number	Hits	Search Text	DB	Time stamp
36	1935	257/668	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:25
37	2685	257/676	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:25
38	684	257/688	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:25
39	320	257/694	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:25
40	1887	257/698	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:25
41	2470	257/737	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:26
42	2015	257/738	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:26
43	248	257/739	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:26
44	2621	257/774	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:26
45	2942	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:26
46	1326	257/779	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:26
47	815	257/782	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:26
48	1245	257/783	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:26
49	2005	257/784	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:26

50	2099	257/786	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:26
51	14924	257/668 257/676 257/688 257/694 257/698 257/737 257/738 257/739 257/774 257/778 257/779 257/782 257/783 257/784 257/786	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:27
52	10970	(257/668 257/676 257/688 257/694 257/698 257/737 257/738 257/739 257/774 257/778 257/779 257/782 257/783 257/784 257/786) and (chip component)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:29
53	1445	((257/668 257/676 257/688 257/694 257/698 257/737 257/738 257/739 257/774 257/778 257/779 257/782 257/783 257/784 257/786) and (chip component)) and ((conduct$3 interconnect$3) near pattern)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:31
54	1285	(((257/668 257/676 257/688 257/694 257/698 257/737 257/738 257/739 257/774 257/778 257/779 257/782 257/783 257/784 257/786) and (chip component)) and ((conduct$3 interconnect$3) near pattern)) and (via hole plug cavity gap)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/03/25 14:31